TOSHIBA Photocoupler IRED & Photo-IC

TLP2200

Isolated Bus Driver
High Speed Line Receiver
Microprocessor System Interfaces
MOS FET Gate Driver
Direct Replacement for HCPL-2200

The TOSHIBA TLP2200 consists of an infrared emitting diode and integrated high gain, high speed photodetector. This unit is 8–lead DIP package.

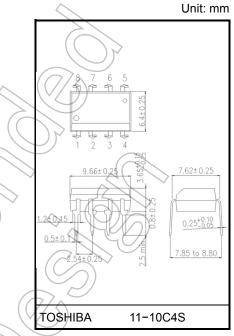
The detector has a three state output stage that eliminates the need for pull–up resistor, and built–in Schmitt trigger. The detector IC has an internal shield that provides a guaranteed common mode transient immunity of $1000V\,/\,\mu s$.

- Input current: IF = 1.6 mA
- Power supply voltage: V_{CC} = 4.5 to 20 V
- Switching speed: 2.5MBd guaranteed
- Common mode transient immunity: ±1000V / µs (min)
- Guaranteed performance over temperature: 0 to 85°C
- Isolation voltage: 2500 Vrms (min)
- UL-recognized: UL 1577, File No.E67349
- cUL-recognized: CSA Component Acceptance Service No.5A

File No.E67349

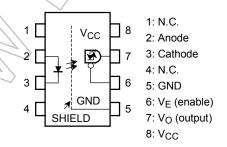
Truth Table (positive logic)

Input	Enable	Output
Н	(H, /,	Z
L	H	Z
Н	L	Н
L	\	L

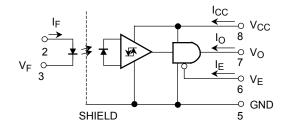


Weight: 0.54 g (typ.)

Pin Configuration (top view)



Schematic



Start of commercial production 1986-07



Recommended Operating Conditions

Characteristic	Symbol	Min	Тур.	Max	Unit
Input current, on	IF(ON)	1.6	1	5	mA
Input current, off	IF(OFF)	0	1	0.1	mA
Supply voltage	Vcc	4.5	1	20	V
Enable voltage high	VEH	2.0	1	20	V
Enable voltage low	VEL	0	_	0.8	V
Fan out (TTL load)	N	_	_	4	
Operating temperature	Topr	0		85	°C (

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Absolute Maximum Ratings (no derating required up to 70°C)

	Characteristic	Symbol	Rating	Unit
	Forward current	lf 🏑 (10	mA (
	Peak transient forward current (Note 1)	IFPT	1	A
ш	Reverse voltage	VR	5	(4//
_	Input Power Dissipation	PD	45	mW
	Input power dissipation derating (Ta ≥ 70°C)	ΔΡ ₀ /ΔΤα	-0.86	mW/°C
	Output current	lo	25	mΑ
_ _	Supply voltage	Vcc	−0.5 to 20	V
c t	Output voltage	Vo	-0.5 to 20	V
Ф	Three state enable voltage	VE	-0.5 to 20	V
e t	Output Power Dissipation	Po	100	mW
	Output Power Dissipation Derating (Ta ≥ 70°C)	ΔP ₀ /°C/	-1.9	mW/°C
	Total package power dissipation (Note 2)	PT	<i>J)</i> 210	mW
Оре	rating temperature range	Topr	−40 to 85	°C
Stor	age temperature range	T _{stg}	−55 to 125	°C
Lead	d solder temperature (10 s) (**)	T _{sol}	260	°C
	ation voltage 60 s, R.H. ≤ 60 %,Ta = 25°C) (Note 3)	BVS	2500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

- (Note 1) Pulse width 1 μ s, 300 pps.
- (Note 2) Derate 4.5 mW / °C above 70 °C ambient temperature.
- (Note 3) Device considered a two terminal device: Pins 1, 2, 3 and 4 shorted together, and pins 5,6,7 and 8 shorted together
 - (**) 1.6 mm below seating plane.

Electrical Characteristics (unless otherwise specified, Ta = 0 to 85 °C, Vcc = 4.5 to 20 V, IF(ON) = 1.6 to 5 mA, IF(OFF) = 0 to 0.1 mA, VEL = 0 to 0.8 V, VEH = 2.0 to 20 V)

Characteristic	Symbol	Test Condition		Min	Typ.*	Max	Unit
Output leakage current	_	I _F = 5 mA,	V _O = 5.5 V	_		100	_
(Vo > Vcc)	Іонн	V _{CC} = 4.5 V	V _O = 20 V	- (2	500	μΑ
Logic low output voltage	V _{OL}	I _{OL} = 6.4 mA (4 TT	L load)		0.32	0.5	V
Logic high output voltage	Voн	I _{OH} = -2.6 mA	\wedge	2.4//	3.4	_	V
Logic low enable current	I _{EL}	V _E = 0.4 V			-0.13	-0.32	mA
		V _E = 2.7 V		7	1	20	
Logic high enable current	IEH	VE = 5.5 V			- /	100	μΑ
		V _E = 20 V	4	> _	0.01	250	
Logic low enable voltage	VEL	-		1		0.8	V
Logic high enable voltage	VEH	-	- (\lambda \lambda \rangle)	2.0	(\bigcirc)		V
Logia law auggly auggent	la a	I _F = 0 mA	V _{CC} = 5.5 V	_	5	6.0	mA
Logic low supply current	ICCL	VE = don't care	Vcc = 20 V	+0	5.6	7.5	
Logic high supply current	Іссн	IF = 5 mA VE = don't care	V _{CC} = 5.5 V		2.5	4.5	mA
			V _{CC} = 20 V	(775)	2.8	6.0	
	lozL	IF = 5 mA VE = 2 V	V _O = 0.4 V		1	-20	
High impedance state	10711	I _F = 0 mA V _E = 2 V	V _O = 2.4 V) —	_	20	μА
output current			V _O = 5.5 V	/ –	-	100	
		,	V _O = 20 V	_	0.01	500	
Logic low short circuit	last	IF ≠ 0 mA	$V_0 = V_{CC} = 5.5 \text{ V}$	25	55	_	mA
output current (Note 4)	losL	TIF F O TITA	$V_0 = V_{CC} = 20 \text{ V}$	40	80	_	ША
Logic high short circuit		IF = 5 mA	V _{CC} = 5.5 V	-10	-25	_	mA
output current (Note 4)	Iosh	Vo = GND	V _{CC} = 20 V	-25	-60	_	ША
Input current hysteresis	IHYS	Vcc = 5 V		1	0.05	_	mA
Input forward voltage	⟩ V _F	I _F = 5 mA, Ta = 25 °C		_	1.55	1.7	V
Temperature coefficient of forward voltage	ΔV _F / ΔTa	I _F = 5 mA		_	-2.0	_	mV / °C
Input reverse breakdown voltage	BVR	I _R = 10 μA, Ta = 25 °C		5	_	_	V
Input capacitance	Cin	V _F = 0 V, f = 1 MHz, Ta = 25 °C		_	45	_	pF
Resistance (input-output)	RI-O	V _{I-O} = 500 V R.H. ≤ 60 % (Note 3)		5×10 ¹⁰	10 ¹⁴	_	Ω
Capacitance (input-output)	C _I -O	V _{I-O} = 0 V, f = 1 M	_	0.6	_	pF	

^(**) All typ. values are at Ta = 25 °C, VCC = 5 V, IF(ON) = 3 mA unless otherwise specified.

Switching Characteristics

(unless otherwise specified, Ta = 0 to 85 °C,Vcc = 4.5 to 20 V,IF(ON) = 1.6 to 5 mA, IF(OFF) = 0 to 0.1 mA)

Characteristic	Symbol	Test Circuit	Test Condition	Min	Тур.	Max	Unit
Propagation delay time to logic high output level	t _{pLH}		Without peaking capacitor C1		235		ns
(Not	te 5)		With peaking capacitor C ₁	(-)	<i>></i> −	400	
Propagation delay time to logic low output level	t _{pHL}	1	Without peaking capacitor C ₁		250	ı	ns
(Not	te 5)		With peaking capacitor C ₁)+	_	400	
Output rise time (10-90%)	t _r			/_	35	-	ns
Output fall time (90-10%)	t _f		- (()>	_	20	-	ns
Common mode transient immunity at logic high output (Not	CM _H	3	I _F = 1.6 mA, V _{CM} = 50 V, Ta = 25 °C	-1000		<u> </u>	V / μs
Common mode transient immunity at logic low output (Not	CM _L	3	I _F = 0 mA, V _{OM} = 50 V, Ta = 25 °C	1000		· _	V / μs

(*) All typ. values are at Ta = 25 °C, VCC = 5 V, IF(ON) = 3 mA unless otherwise specified

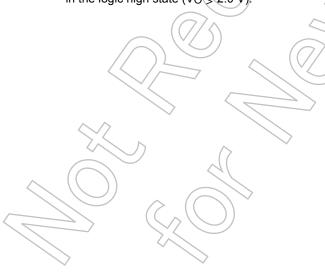
(Note 4) Duration of output short circuit time should not exceed 10ms.

(Note 5) The t_{pLH} propagation delay is measured from the 50 % point on the leading edge of the input pulse to the 1.3 V point on the leading edge of the output pulse.

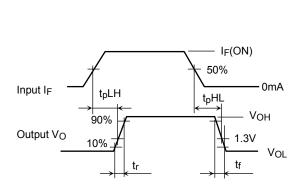
The t_{pHL} propagation delay is measured from the 50 % point on the trailing edge of the input pulse to the 1.3 V point on the trailing edge of the output pulse.

(Note 6) CML is the maximum rate of rise of the common mode voltage that can be sustained with the output voltage in the logic low state ($V_O < 0.8 \text{ V}$).

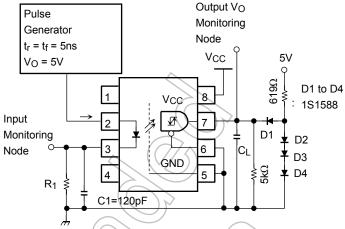
CMH is the maximum rate of fall of the common mode voltage that can be sustained with the output voltage in the logic high state (VO > 2.0 V).



Test Circuit 1 tpHL, tpLH, tr and tf



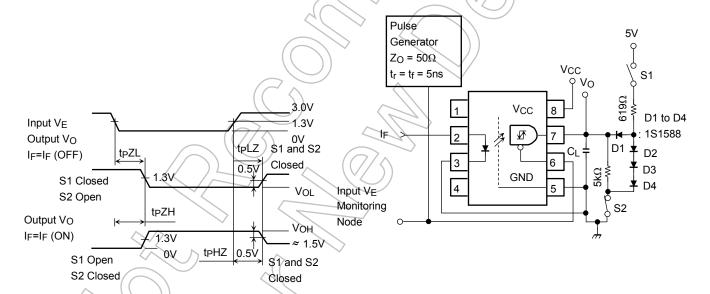
R ₁	2.15kΩ	1.1kΩ	681Ω
I _F (ON)	1.6mA	3mA	5mA



C₁ is peaking capacitor. The probe and jig capacitances are included in C₁.

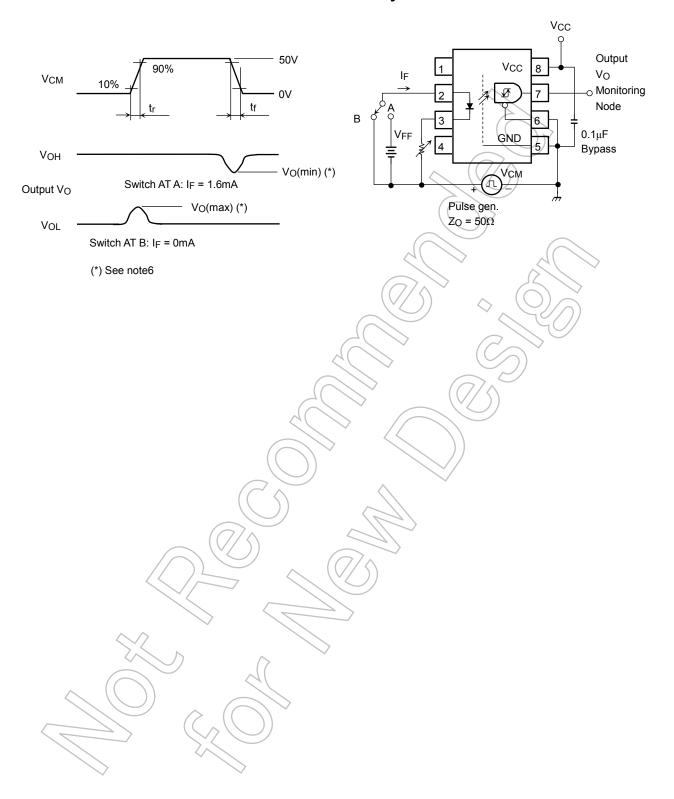
C_L is approximately 15pF which includes probe and stray wiring capacitance.

Test Circuit 2 tpHz, tpZH, tpLz and tpZL



C_L is approximately 15pF which includes probe and stray wiring capacitance.

Test Circuit 3 Common Mode Transient Immunity



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